



Final Product/Process Change Notification

Document #:FPCN24888XC

Issue Date:15 Nov 2023

| | |
|--|--|
| Title of Change: | DPAK case outline 369C - Assembly and Test Qualification to JCET Semiconductor (Suqian) Co.Ltd., China for Capacity Expansion |
| Proposed First Ship date: | 20 Feb 2024 or earlier if approved by customer |
| Contact Information: | Contact your local onsemi Sales Office |
| PCN Samples Contact: | Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements. |
| Additional Reliability Data: | Contact your local onsemi Sales Office or MohdAzizi.Azman@onsemi.com |
| Type of Notification: | This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com |
| Marking of Parts/ Traceability of Change: | Changed material can be identified by assembly plant code. |
| Change Category: | Test Change, Assembly Change |
| Change Sub-Category(s): | Material Change, Manufacturing Site Transfer |

| | |
|------------------------|--------------------------------------|
| Sites Affected: | |
| onsemi Sites | External Foundry/Subcon Sites |
| None | JCET, China |

Description and Purpose:

This Final Notification announces to customers the qualification of new assembly and test site of DPAK package (Case Outline 369C) products to JCET Semiconductor (Suqian) Co.Ltd., China.

| | From | To |
|----------------------------|---------------------------|--|
| Assembly & Final Test Site | onsemi Seremban, Malaysia | JCET Semiconductor (Suqian) Co.Ltd., China |
| Lead Frame | LF DPAK Single Gauge | TO-252-2L(6R) (Bare Cu), stamped |
| Die Attach | Pb95Sn5 | 92.5%Pb,2.5%Sn,5%Ag |

There is no product marking change as a result of this change.



Final Product/Process Change Notification

Document #:FPCN24888XC

Issue Date:15 Nov 2023

Reliability Data Summary:

QV DEVICE NAME: NSV50150ADT4G

RMS: S92218

PACKAGE: DPAK 3L

| Test | Specification | Condition | Interval | Results |
|---|------------------------------|--|-----------|---------|
| High Temperature Operating Life | JESD22-A108 | Ta=125°C, 100 % max rated Vcc | 1008 hrs | 0/231 |
| High Temperature Storage Life | JESD22-A103 | Ta= 150°C | 1008 hrs | 0/231 |
| Preconditioning | J-STD-020 JESD-A113 | MSL 1 @ 260°C, Pre TC, uHAST, THB, IOL for surface mount pkgs only | | 0/924 |
| Temperature Cycling | JESD22-A104 | Ta= -65°C to +150°C, mount on board | 500 cyc | 0/231 |
| Intermittent Operating Life | MIL-STD-750 (M1037) AEC-Q101 | Ta=+25°C, delta Tj=100°C On/off = 2 min | 15000 cyc | 0/231 |
| Temperature Humidity Bias | JESD22-A101 | 85°C, 85% RH, bias | 1008 hrs | 0/231 |
| Unbiased Highly Accelerated Stress Test | JESD22-A118 | 130°C, 85% RH, 18.8psig, unbiased | 96 hrs | 0/231 |
| Resistance to Solder Heat | JESD22- B106 | Ta = 265°C, 10 sec Required for through hole devices only | | 0/90 |
| Solderability | JSTD002 | Ta = 245°C, 5 sec | | 0/45 |

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

| Part Number | Qualification Vehicle |
|---------------|-----------------------|
| NSI50150ADT4G | NSV50150ADT4G |
| NSI45090JDT4G | NSV50150ADT4G |
| NSI45060JDT4G | NSV50150ADT4G |